L	Hits	Search Text	DB	Time stamp
Number				
1	1	356/399,400.ccls. and laser and (notch or	USPAT;	2004/02/03
		hole or fiducial) and (wafer or	US-PGPUB;	17:07
		semiconductor) and @pd>20040112	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	23		USPAT;	2004/02/03
		(notch or hole or fiducial) and (wafer or	US-PGPUB;	17:11
		semiconductor) and @pd>20030821	EPO; JPO;	
			DERWENT;	1
			IBM_TDB	
3	9	356/630-632,426,504.ccls. and laser and	USPAT;	2004/02/03
		(notch or hole or fiducial) and (wafer or	US-PGPUB;	17:10
		semiconductor) and @pd>20030821	EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	0004/00/00
4	5	,,	USPAT;	2004/02/03
		hole or fiducial) and (wafer or	US-PGPUB;	17:10
		semiconductor) and @pd>20030821	EPO; JPO;	
			DERWENT;	
	0	427/0 10	IBM_TDB USPAT;	2004/02/03
5	U	427/9,10.ccls. and laser and (notch or	US-PGPUB;	17:10
		hole or fiducial) and (wafer or	EPO; JPO;	17:10
		semiconductor) and @pd>20030821	DERWENT;	
			IBM TDB	
6	1	250/231.14-231.17.ccls. and laser and	USPAT;	2004/02/03
٠	1	(notch or hole or fiducial) and (wafer or	US-PGPUB;	17:11
		semiconductor) and @pd>20030821	EPO; JPO;	- / •
		Semiconductor, and Gpaszoosoozi	DERWENT;	
			IBM TDB	
7	35	356/614.ccls. and laser and (notch or	USPAT;	2004/02/03
	33	hole or fiducial) and (wafer or	US-PGPUB;	17:12
		semiconductor)	EPO; JPO;	
			DERWENT;	
			IBM TDB	